

HIGH-DENSITY INTER-DIE INTERCONNECT STRUCTURE

ABSTRACT

An interconnect architecture for connecting a plurality of closely-spaced electrical elements on a first integrated circuit fabricated structure with operative circuits on a second integrated circuit fabricated structure. In one embodiment, the first integrated circuit fabricated structure comprises a plurality of photo sensors. Conductive interconnect elements on the first integrated circuit fabricated structure provide electrical connection between individual photo sensors and the operative circuitry on the second integrated circuit fabricated structure.

Figure 1



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